Analog Power AM2317P

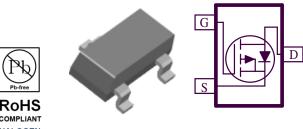
P - Channel Logic Level MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

•	Low $r_{DS(\text{on})}$ provides higher efficiency and
	extends battery life

- Low thermal impedance copper leadframe SOT-23 saves board space
- Fast switching speed
- High performance trench technology

PRODUCT SUMMARY				
V _{DS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)		
-30	$0.30 @ V_{GS} = -10 V$	-1.0		
-30	$0.50 @ V_{GS} = -4.5V$	-0.9		



Pb-free
RoHS
COMPLIAN
HALOGE
FREE

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED)					
Parameter			Maximum	Units	
Drain-Source Voltage			-30	V	
Gate-Source Voltage			±20	V	
Continuous Drain Current ^a	$T_A=25^{\circ}C$		±0.9		
Continuous Drain Current	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	ъ	±0.75	A	
Pulsed Drain Current ^b	I_{DM}	±10			
Continuous Source Current (Diode Conduction) ^a			0.4	A	
D D: a	$T_A=25^{\circ}C$	D	0.5	w	
Power Dissipation ^a	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	P_{D}	0.42	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Maximum	Units		
a a	t <= 5 sec	D	250	0000	
Maximum Junction-to-Ambient"	Steady-State	R_{THJA}	285	°C/W	

1

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)							
D		T . C . 11.1	Limits			T T 1.	
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Switch Off Characteristics							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \text{ uA}$	-30				
Zana Cata Valtaga Dunin Cumant	T	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$			-1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			-10	μΑ	
Gate-Body Leakage	Igss	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			±100	nA	
Switch On Characteristics							
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250 \text{ uA}$	-0.80	-1.7	-2.6	V	
On-State Drain Current ^A	ID(on)	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-2			A	
		$V_{GS} = -10 \text{ V}, I_D = -1.0 \text{ A}$		0.25	0.30		
Drain-Source On-Resistance ^A	rDS(on)	$V_{GS} = -4.5 \text{ V}, I_{D} = -0.9 \text{ A} \text{ T}_{J} = 55^{\circ} \text{C}$		0.53	0.66	Ω	
		$V_{GS} = -4.5 \text{ V}, I_D = -0.9 \text{ A}$		0.45	0.50		
Forward Tranconductance ^A	gfs	$V_{DS} = -5 \text{ V}, I_{D} = -1.1 \text{ A}$		2		S	
Diode Forward Voltage	V_{SD}	$I_S = -0.4 \text{ A}, V_{GS} = 0 \text{ V}$		-0.70	-1.2	V	
Dynamic ^b							
Total Gate Charge	Qg	101/11/2011		2.0	3.0		
Gate-Source Charge	Qgs	$V_{DS} = -10 \text{ V}, V_{GS} = -5 \text{ V},$		0.5		nC	
Gate-Drain Charge	Q_{gd}	$I_D = -0.9 \text{ A}$		1.1			
Switching							
Turn-On Delay Time	t _{d(on)}			8	16		
Rise Time	$t_{\rm r}$	$V_{DS} = -10 \text{ V}, I_D = -0.9 \text{ A},$		16	32	ns	
Turn-Off Delay Time	td(off)	$R_G = 50 \Omega$, $V_{GEN} = -10 V$		36	93	115	
Fall-Time	t_{f}			33	94		

Notes

- a. Pulse test: $PW \le 300$ us duty cycle $\le 2\%$.
- b. Guaranteed by design, not subject to production testing.

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Typical Electrical Characteristics

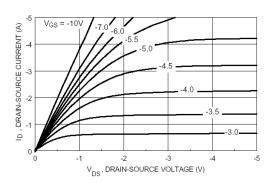


Figure 1. On-Region Characteristics

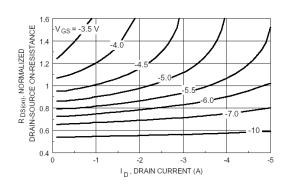


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

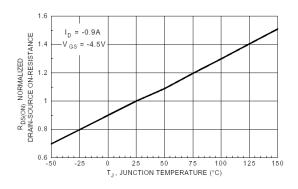


Figure 3. On-Resistance Variation with Temperature

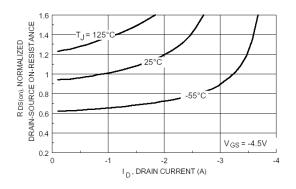


Figure 4. On-Resistance Variation with Gate to Source Voltage

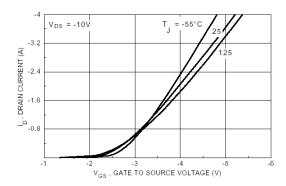


Figure 5. Transfer Characteristics

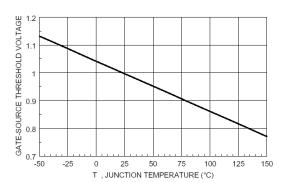
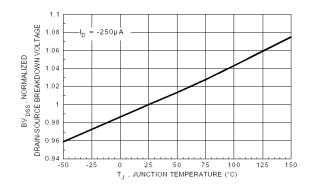


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

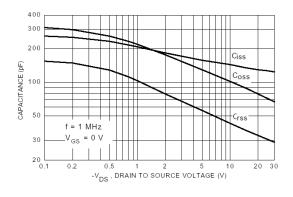
Typical Electrical Characteristics



0.0001 0.0001

Figure 7. Breakdown Voltage With Temperature

Figure 8. Body Diode Forward Voltage With Source Current & Temperature



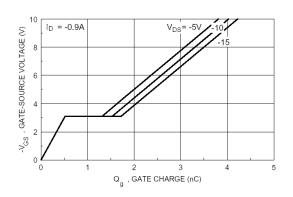


Figure 9. Capacitance Characteristic

Figure 10. Gate Charge Characteristic

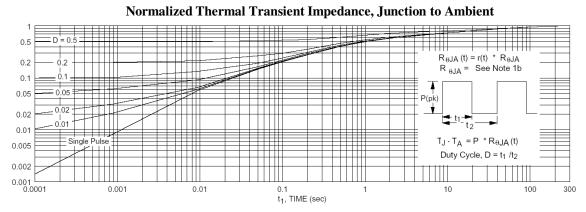


Figure 11. Transient Thermal Response Curve

Typical Electrical Characteristics

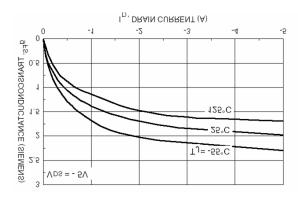


Figure 13. Transconductance Variation With Current & Temperature

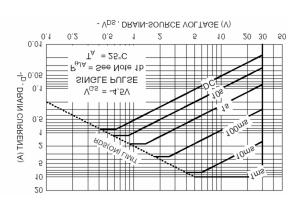


Figure 14. Maximum Safe Operation Area

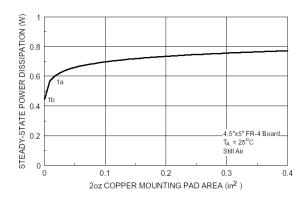


Figure 15. SOT-3 Maximum Steady-State Variation Power Dissipation versus Copper Pad Area

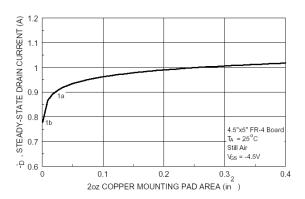
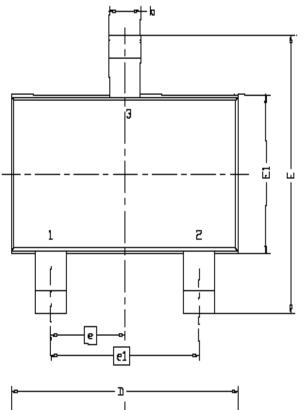


Figure 16. Maximum State-State Drain Current Versus Copper Pad Area

Package Information



DIM.	MILLIMETERS				
יווות	MIN	NDM	MAX		
Α	0.935	0.95	1.10		
A1	0.01		0.10		
A2	0.85	0.90	0.925		
Ь	0.30	0.40	0.50		
С	0.10	0.15	0,25		
D	2.70	2.90	3.10		
Ε	2.60	2.80	3.00		
E1	1.40	1.60	1.80		
6	0.95 BSC				
el	1.90 BSC				
L	0.30	0.40	0.60		
L1	0.60REF				
L2	0,25BSC				
R	0.10	-			
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81	7*N□M				

